

Surface Mount Ultra Fast Rectifiers

Features

- Low profile package
- Ideal for automated placement
- Glass passivated chip junctions
- Ultrafast reverse recovery time
- Low switching losses, high efficiency
- High forward surge capability
- High temperature soldering:
 260°C/10 seconds at terminals
- Component in accordance to RoHS 2002/95/1 and WEEE 2002/96/EC



- Case: JEDEC MSMA molded plastic body over glass passivated chip
- Terminals: Solder plated, solderable per J-STD-002B and JESD22-B102D
- Polarity: Laser band denotes cathode end





Major Ratings and Characteristics

I _{F(AV)}	1.0 A				
V _{RRM}	50 V to 1000 V				
I _{FSM}	30 A				
t _{rr}	50nS, 75nS				
V _F	1.0 V, 1.3 V, 1.7 V				
T _j max.	150 °C				

Maximum Ratings & Thermal Characteristics

(T_A = 25 °C unless otherwise noted)

Items	Symbol	MAHE 1A	MAHE 1B	MAHE 1D	MAHE 1G	MAHE 1J	MAHE 1K	MAHE 1M	UNIT
Maximum repetitive peak reverse voltage	V_{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS voltage	V_{RMS}	35	70	140	280	420	560	700	V
Maximum DC blocking voltage	V_{DC}	50	100	200	400	600	800	1000	V
Maximum average forward rectified current	I _{F(AV)}	1.0					Α		
Peak forward surge current 8.3 ms single half sine-wave superimposed on rated load	I _{FSM}	30					Α		
Thermal resistance from junction to lead ⁽¹⁾	$R_{\theta JL}$	35						°C/W	
Operating junction and storage temperature range	T _J , T _{STG}	_55 to +150						$^{\circ}\!$	

Note 1: Mounted on P.C.B. with 0.2 x 0.2" (5.0 x 5.0mm) copper pad areas.

Electrical Characteristics (T_A = 25 °C unless otherwise noted)

Items	Test co	onditions	Symbol	mbol MAHE1A~ MA		MAHE1J~ MAHE1M	UNIT
Instantaneous forward voltage	I _F =1	I _F =1.0A ⁽²⁾ V _F		1.0	1.3	1.7	V
Reverse current	V _R =V _{DC}	T _A =25℃ T _A =125℃	I _R	5 100			μΑ
Reverse recovery time	I _F = 0.5 A I _{rr} = 0	, I _R = 1.0 A , 0.25 A	t _{rr}	50		75	nS
Typical junction capacitance	4.0V,1.0MHz		CJ	15		10	pF

Note 2: Pulse test:300µs pulse width,1% duty cycle.



Surface Mount Ultra Fast Rectifiers

Characteristic Curves (T_A=25 ℃ unless otherwise noted)

Fig.1 Forward Current Derating Curve 1.0 Average Forward Current (A) 0.8 0.6 0.4 0.2 0 0 30 60 90 120 150 Lead Temperature (で)

Fig.3 Typical Instantaneous Forward Characteristics

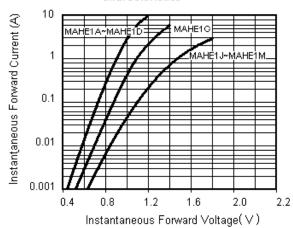
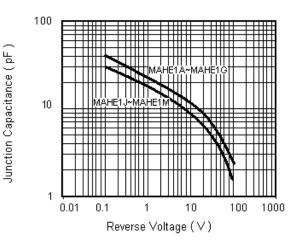


Fig.5 Typical Junction Capacitance



Forward Surge Current 30

Fig.2 Maximum Non-Repetitive Peak

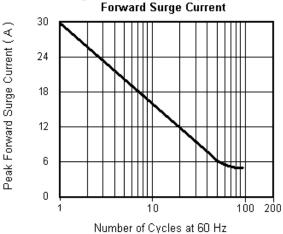


Fig.4 Typical Reverse Leakage Characteristics

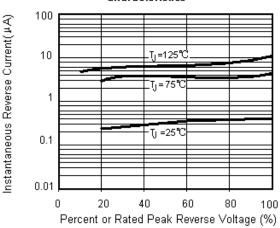
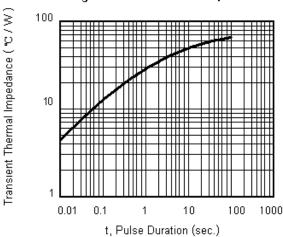


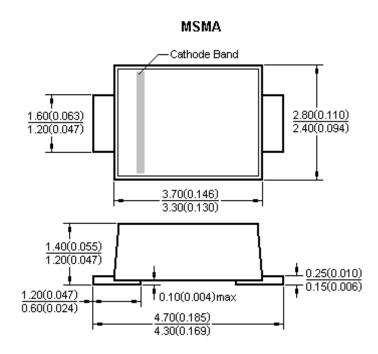
Fig.6 Transient Thermal Impedance





Surface Mount Ultra Fast Rectifiers

Package Outline



Dimentsions in millimeters and (inches)

Notice

- Product is intended for use in general electronics applications.
- Product should be worked less than the ratings; if exceeded, may cause permanent damage.or introduce latent failure mechanisms.
- The absolute maximum ratings are rated values and must not be exceeded during operation. The following are the general derating methods you design a circuit with a device.
 - $I_{\text{F(AV)}}\!:\!\text{We recommend that the worst case current be no greater than 80%}$.
 - I_{FSM}: This rating specifies the non-repetitive peak current. This is only applied for an abnormal operation, which the general during the lifespan of the device.
 - T_J: Derate this rating when using a device in order to ensure high reliability. We recommend that the device be used at a T_J of below 125°C.
- TRR is registered trademark of Rising-sun Technology. Rising-sun Technology reserves the right to make changes to any product in this
 specification to improve reliability, functional characteristics, or design without notice.
- Rising-sun Technology does not assure any liability arising out of the applications or any product described in this specification.
- Rising-sun Technology advises customers to obtain the latest version of the device information before placing orders to verify that the
 required information is current.